X6600

X6600 is a cost-effective and precise micro-focus X-ray inspection equipment for the off-line inspection of various micro-electronics , and electromechanical products. It has the characteristics of high magnification, multi-angle inspection, large area inspection and reliability.

Parameters

Dimension	L1360mm×W1240mm×H1700mm
Power Supply	220V 10A/110V 15A 50-60HZ
Max Sample Size	540mm×440mm
OS	IPC WIN7/ WIN10 64 bit
N.W.	About 1170KG

Advantages

◆ Universal model for different inspection applications

◆ Fast acquisition of High-Resolution Images

◆ Quick IR auto-navigation and positioning

◆ CNC automatic inspection mode for multi-point array

◆ Easy to inspect defects in tilt and multi-angle mode

◆ User-friendly software operation, resulting in low training costs

◆ Xray tube and FPD support to rotate simultaneously (0-60°) to get clear and intuitive image

X-ray Tube Spec

|	
TubeType	Reflective sealed micro-focus ray source
Tube Voltage	40-90KV/130KV
Tube Current	10-200 µA/10-300 µA
Max Output Power	8 W/39W
Micro Focus Size	5~15µm

FPD Spec

|	
Detector Type	Amorphous silicon flat panel detector
Pixel Matrix	1536×1536
FOV	130mm×130mm
Resolution	5.8Lp/mm
Image frame rate (1×1))	20fps
AD conversion digits	16bit

Dimensions

1887
1624
1256
1587
1236
1733
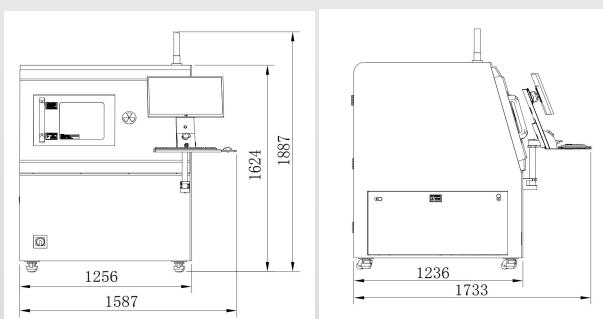
Automatic void ratio calculation

■ Extended BGA detection function with quick select/mark/inspection of single ball or multiple balls in a matrix frame. Manually or automatically ID BGA solder balls and complete the inspection. Simple operation with accurate inspection results.
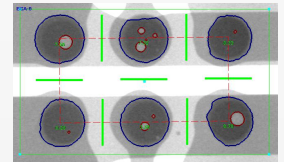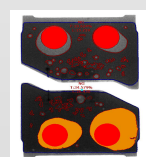
Size measurement

■ Measuring tools:
Distance, distance ratio, line spacing, angle, arrow mark, circle radius, dot spacing, center distance, circumference, hand-drawn polygon, hand-drawn free-form, text.
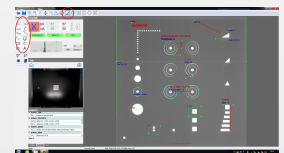
Defects Inspection

■ Automatic defect recognition:X6600/X5600 can automatically identify size, area disconnection, and tin connection.
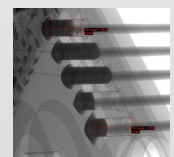
■ Customizable image algorithms.
According to the customer's product characteristics and requirements, specific software algorithms are developed to realize automatic defect recognition and detection functions, including recognition algorithms for presence, crack, disconnection, offset, size, and how many.

LED pad measurement
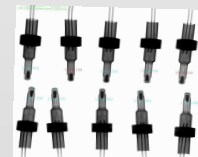
Sensor size measurement

THT tin ration measurement